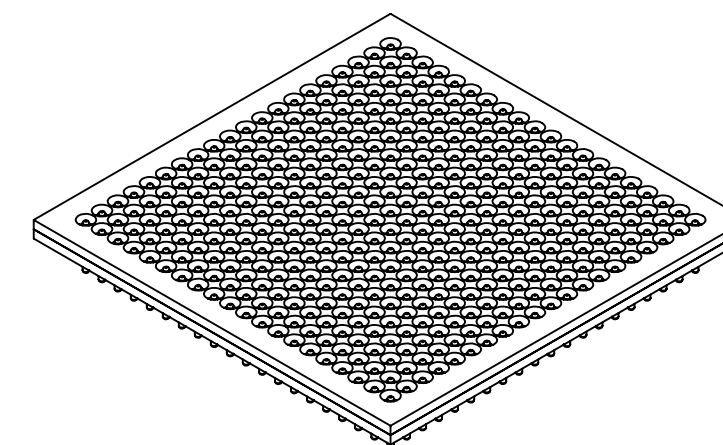


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REVISION HISTORY				
REV	DESCRIPTION	DCO	DATE	APRVD
1	SALES RELEASE	--		

NOTES:

- INSULATOR MATERIAL: FR4, BLACK.
- PIN MATERIAL: PHOSPHOR BRONZE. PIN PLATING: 10μ" GOLD OVER 50μ" NICKEL.
- REFER TO ISI HiLo APPLICATION GUIDELINES FOR LAND PATTERN, STENCIL DESIGN, AND KEEP OUT ZONE RECOMMENDATIONS.

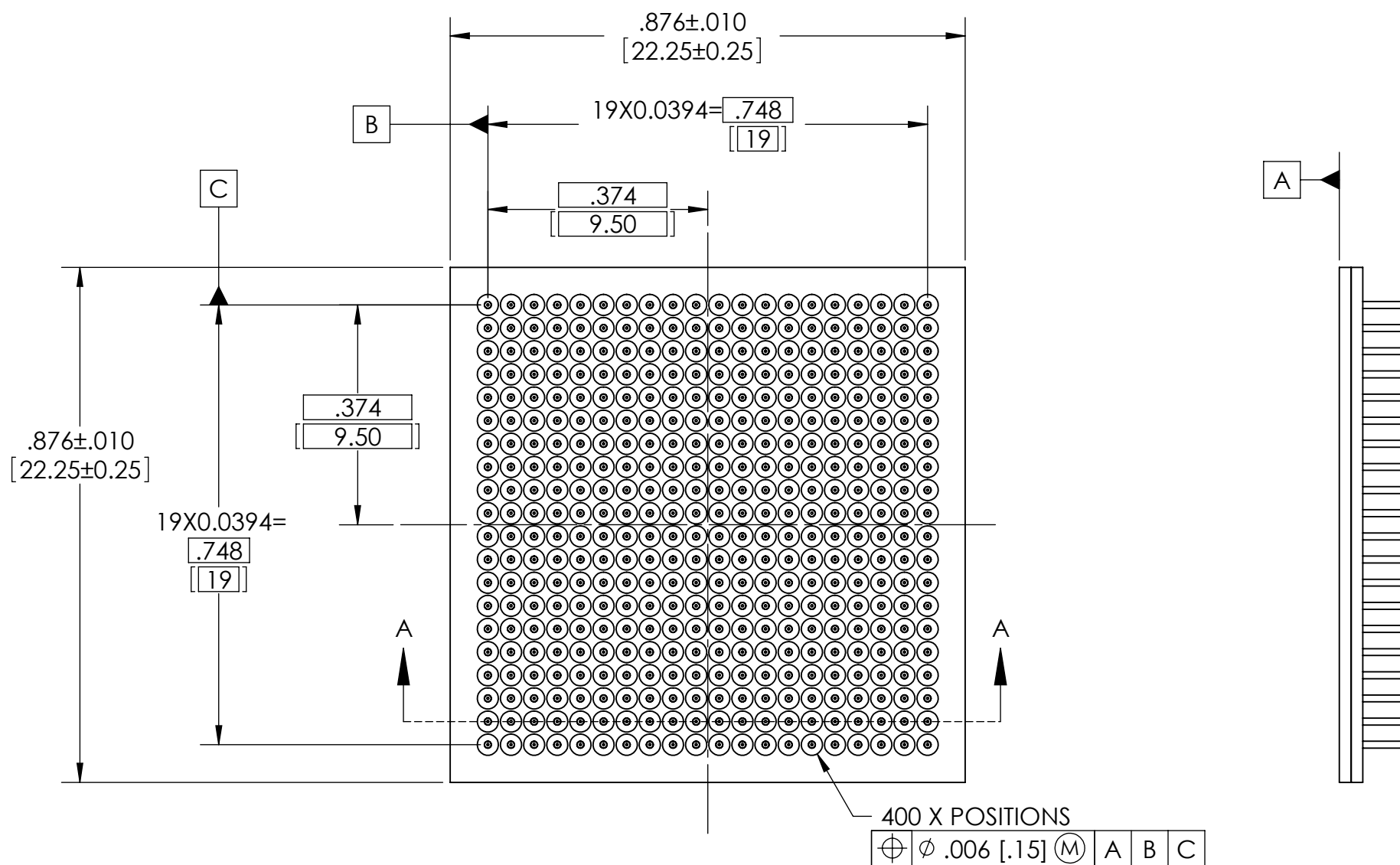


APPROVAL OF THIS DRAWING AUTHORIZES INTERCONNECT SYSTEMS INC. TO PRODUCE PARTS AS OUTLINED HEREIN.

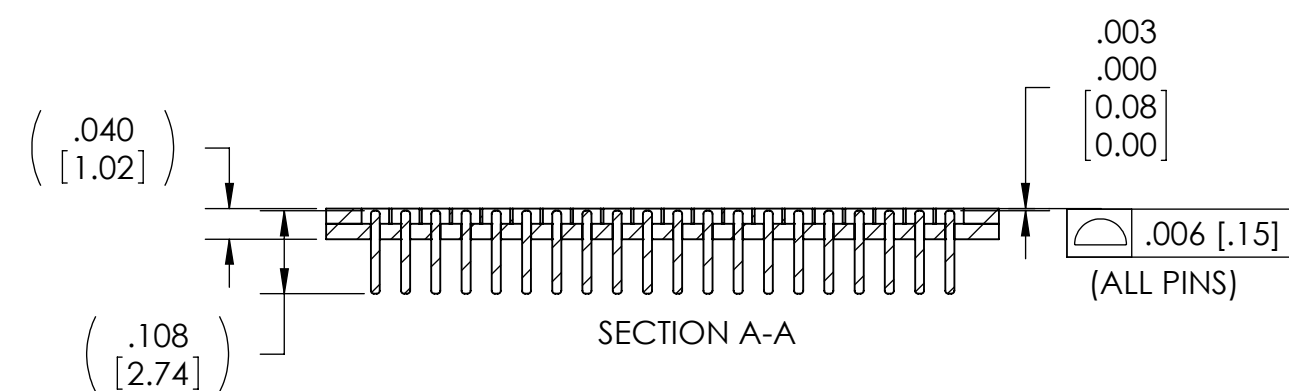
PRINTED NAME: _____

APPROVAL: _____

DATE: _____



400 X POSITIONS
 $\text{⊕ } \text{⌀ } .006 [.15] \text{ (M) } A \ B \ C$



$\text{⊕ } .006 [.15]$
 (ALL PINS)

THIRD ANGLE PROJECTION

CONTRACT NO.
 DRAWN BY P.GUNDALA DATE 06/26/09
 DESIGNER P.GUNDALA DATE 06/26/09
 CHECKER DATE

INTERCONNECT SYSTEMS INC.
 759 FLYNN ROAD, CAMARILLO, CA 93012

UNLESS OTHERWISE SPECIFIED:
 DIMENSIONS ARE: IN INCHES [MILLIMETERS]
 TOLERANCES ARE:
 DECIMALS: .XX ± .010 .XXX ± .005 .XXXX ± .0005 [X] ± .025 [XX] ± .013 [XXX] ± .013
 ANGLES: ± 10°
 FRACTIONS: ± 1/64

QA DATE
 PROCESS ENG. DATE

TITLE **HiLo PIN FIELD ASSEMBLY, FR4 20X20 ARRAY 400 PINS .0394" [1 MM] PITCH**

SIZE B	SCALE 4:1	DRAWING NO. HLP-200400-B-10	REV -+
SAVED AS: HLP-200400-B-10-SALES.SLDDRW		FINISHED ASSY:	Sheet 1 OF 1